Vincotech

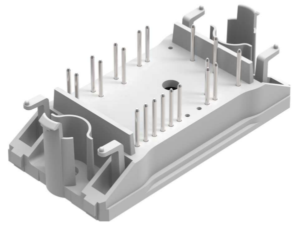
10-F012PNA015M7-P840C29
datasheet

*flow*PIM 0	1200 V / 15 A

Features

- IGBT M7 with low V_{CEsat} and improved EMC behavior
- Open emitter configuration
- Compact and low inductive design
- Built-in NTC

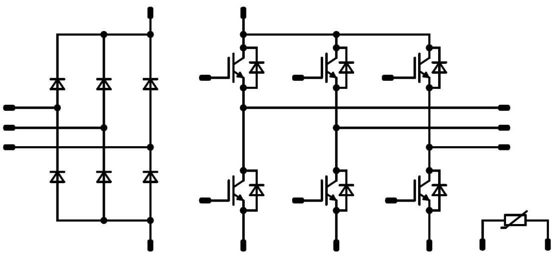
flow 0 17 mm housing



Target applications

- Industrial Drives

Schematic



Types

- 10-F012PNA015M7-P840C29

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Switch				
Collector-emitter voltage	V_{CES}		1200	V
Collector current	I_C		15	A
Repetitive peak collector current	I_{CRM}	t_p limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	60	W
Gate-emitter voltage	V_{GES}		±20	V
Maximum junction temperature	T_{jmax}		175	°C

Maximum Ratings

T_j = 25 °C, unless otherwise specified

Parameter	Symbol	Condition	Value	Unit
Inverter Diode				
Peak repetitive reverse voltage	V_{RRM}		1200	V
Continuous (direct) forward current	I_F		15	A
Repetitive peak forward current	I_{FRM}	T_j limited by T_{jmax}	30	A
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	45	W
Maximum junction temperature	T_{jmax}		175	°C
Rectifier Diode				
Peak repetitive reverse voltage	V_{RRM}		1600	V
Continuous (direct) forward current	I_F		25	A
Surge (non-repetitive) forward current	I_{FSM}	50 Hz Single Half Sine Wave t_p = 10 ms T_j = 150 °C	200	A
Surge current capability	I^2t		200	A^2s
Total power dissipation	P_{tot}	$T_j = T_{jmax}$ T_s = 80 °C	44	W
Maximum junction temperature	T_{jmax}		150	°C
Module Properties				
Thermal Properties				
Storage temperature	T_{stg}		-40…+125	°C
Operation temperature under switching condition	T_{jop}		-40…(T_{jmax} - 25)	°C
Isolation Properties				
Isolation voltage	V_{isol}	DC Test Voltage* t_p = 2 s	6000	V
		AC Voltage t_p = 1 min	2500	V
Creepage distance			min. 12,7	mm
Clearance			min. 12,7	mm
Comparative Tracking Index	CTI		> 200	

*100 % tested in production

Characteristic Values

Parameter	Symbol	Conditions	V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	Unit
Inverter Switch										
Static										
Gate-emitter threshold voltage	$V_{GE(th)}$			10	0,0015	25	5,4	6,0	6,6	V
Collector-emitter saturation voltage	V_{CEsat}		15		15	25 125 150		1,70 1,95 2,01	2,15	V
Collector-emitter cut-off current	I_{CES}		0	1200		25			60	µA
Gate-emitter leakage current	I_{GES}		20	0		25			500	nA
Internal gate resistance	r_g							none		Ω
Input capacitance	C_{ies}		0	10		25		2900		pF
Output capacitance	C_{oes}							120		
Reverse transfer capacitance	C_{res}							34		
Gate charge	Q_g		15	600	15	25		110		nC
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,60		K/W
Dynamic										
Turn-on delay time	$t_{d(on)}$	R_{gon} = 32 Ω R_{goff} = 32 Ω	±15	600	15	25 150		176 174		ns
Rise time	t_r					25 150		43 48		
Turn-off delay time	$t_{d(off)}$					25 150		191 218		
Fall time	t_f					25 150		119 127		
Turn-on energy (per pulse)	E_{on}	Q_{rFWD} = 1,5 µC Q_{rFWD} = 2,6 µC				25 150		1,548 2,008		mWs
Turn-off energy (per pulse)	E_{off}					25 150		0,925 1,322		

Characteristic Values

Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Inverter Diode										
Static										
Forward voltage	V_F				15	25 125 150		1,63 1,74 1,73	2,1	V
Reverse leakage current	I_R			1200		25			30	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						2,11		K/W
Dynamic										
Peak recovery current	I_{RRM}	di/dt = 293 A/µs di/dt = 244 A/µs	±15	600	15	25 150		11 12		A
Reverse recovery time	t_{rr}					25 150		265 423		ns
Recovered charge	Q_r					25 150		1,549 2,592		µC
Reverse recovered energy	E_{rec}					25 150		0,488 0,938		mWs
Peak rate of fall of recovery current	$(di_{rf}/dt)_{max}$					25 150		92 52		A/µs
Rectifier Diode										
Static										
Forward voltage	V_F				25	25 125		1,22 1,21		V
Reverse leakage current	I_R			1600		25			50	µA
Thermal										
Thermal resistance junction to sink	$R_{th(j-s)}$	λ_{paste} = 3,4 W/mK (PSX)						1,59		K/W

Characteristic Values

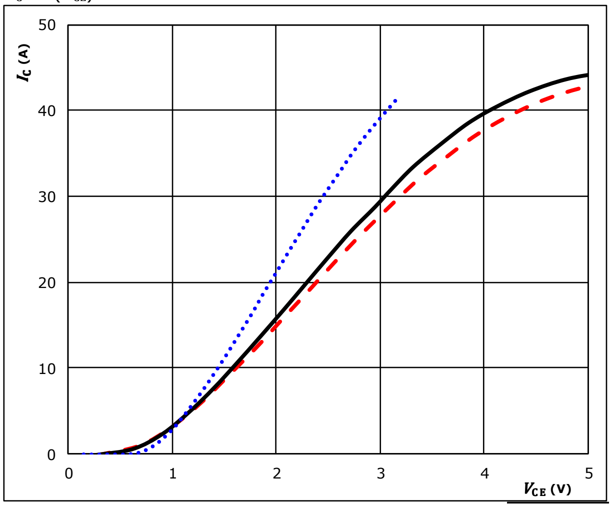
Parameter	Symbol	Conditions					Value			Unit
			V_{GE} [V] V_{GS} [V]	V_{CE} [V] V_{DS} [V] V_F [V]	I_C [A] I_D [A] I_F [A]	T_j [°C]	Min	Typ	Max	
Thermistor										
Rated resistance	R					25		22		kΩ
Deviation of R_{100}	$\Delta_{R/R}$	R_{100} = 1484 Ω				100	-5		5	%
Power dissipation	P					25		5		mW
Power dissipation constant						25		1,5		mW/K
B-value	$B_{(25/50)}$	Tol. ±1 %				25		3962		K
B-value	$B_{(25/100)}$	Tol. ±1 %				25		4000		K
Vincotech NTC Reference									I	

Inverter Switch Characteristics

figure 1. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

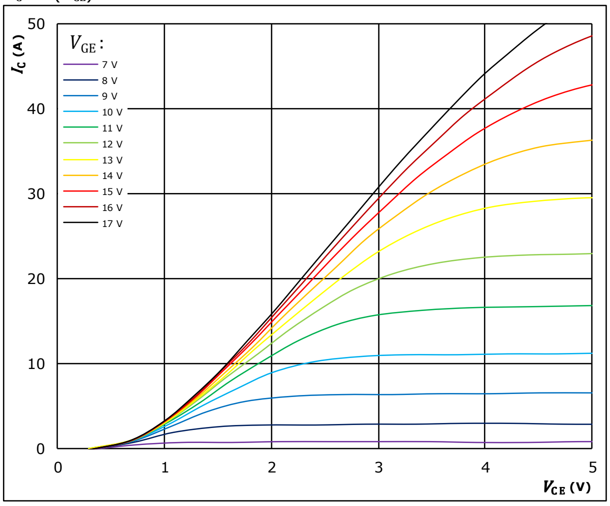


t_p =	250	µs		25 °C	··········
V_{GE} =	15	V	T_j:	125 °C	———
				150 °C	– – –

figure 2. **IGBT**

Typical output characteristics

$I_C = f(V_{CE})$

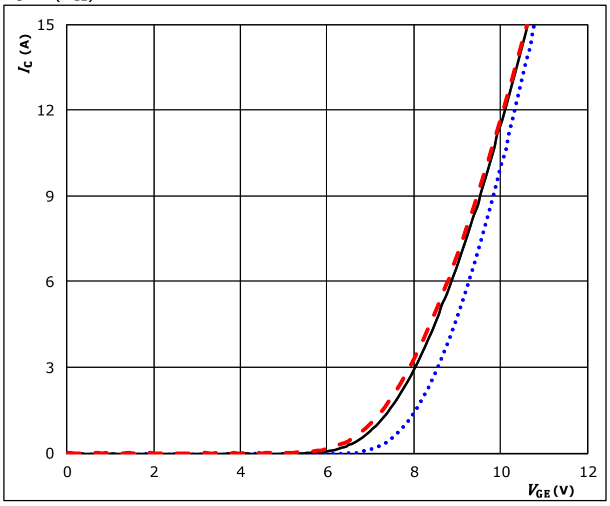


t_p =	250	µs
T_j =	150	°C
V_{GE} from	7 V to 17 V in steps of 1 V	

figure 3. **IGBT**

Typical transfer characteristics

$I_C = f(V_{GE})$

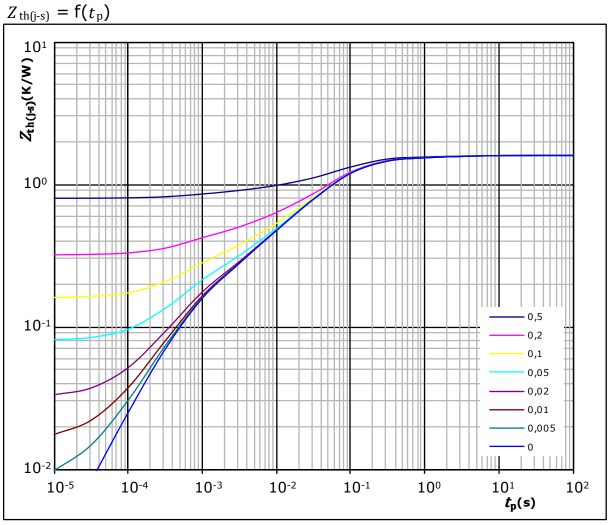


t_p =	100	µs		25 °C	··········
V_{CE} =	10	V	T_j:	125 °C	———
				150 °C	– – –

figure 4. **IGBT**

Transient thermal impedance as function of pulse duration

$Z_{th(j\text{-}s)} = f(t_p)$



D = t_p / T

$R_{th(j\text{-}s)}$ = 1,60 K/W

IGBT thermal model values

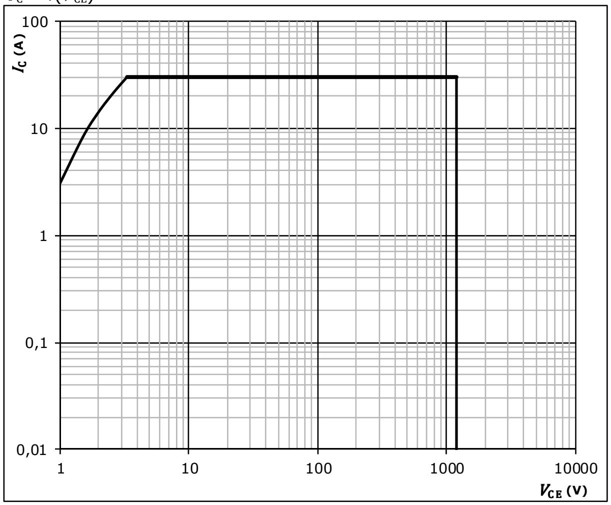
R (K/W)	τ (s)
4,90E-02	4,40E+00
1,40E-01	5,34E-01
8,04E-01	8,02E-02
2,98E-01	2,57E-02
1,69E-01	5,09E-03
1,35E-01	6,41E-04

Inverter Switch Characteristics

figure 5.	IGBT

Safe operating area

$I_C = f(V_{CE})$



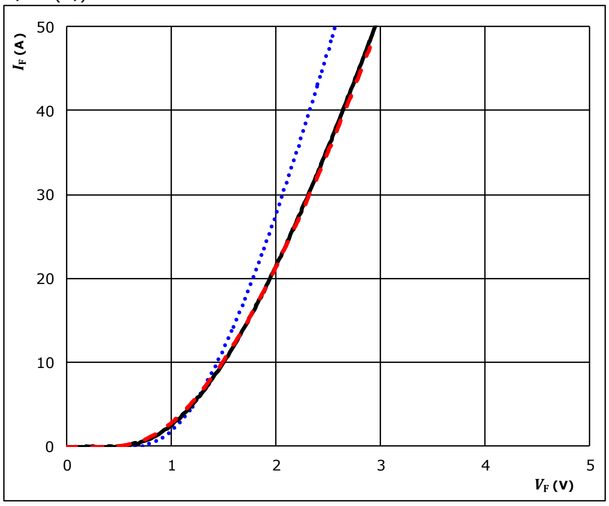
D =	single pulse	
T_s =	80	ºC
V_{GE} =	±15	V
T_j =	T_{jmax}	

Inverter Diode Characteristics

figure 1. **FWD**

Typical forward characteristics

$I_F = f(V_F)$



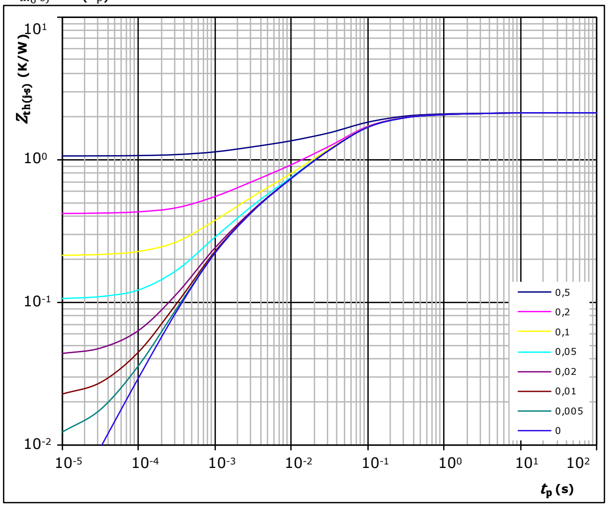
t_p = 250 µs

T_j: 25 °C, 125 °C, 150 °C

figure 2. **FWD**

Transient thermal impedance as a function of pulse width

$Z_{th(j\text{-}s)} = f(t_p)$



$D = t_p / T$

$R_{th(j\text{-}s)}$ = 2,11 K/W

FWD thermal model values

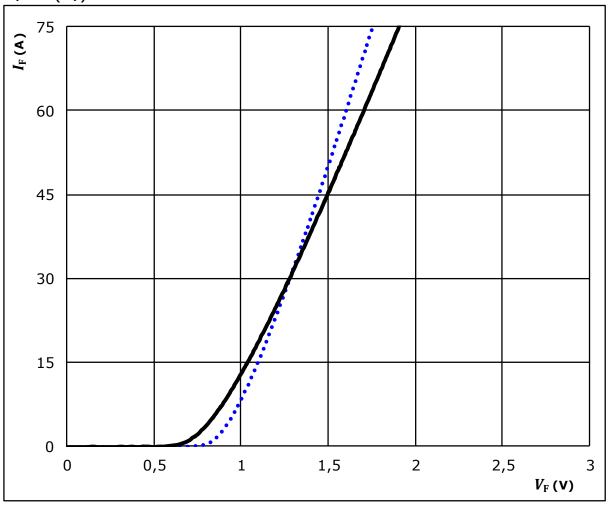
R (K/W)	τ (s)
8,99E-02	2,33E+00
4,04E-01	1,91E-01
1,05E+00	4,49E-02
3,39E-01	6,08E-03
2,29E-01	1,02E-03

Rectifier Diode Characteristics

figure 1. **Rectifier Diode**

Typical forward characteristics

$I_F = f(V_F)$



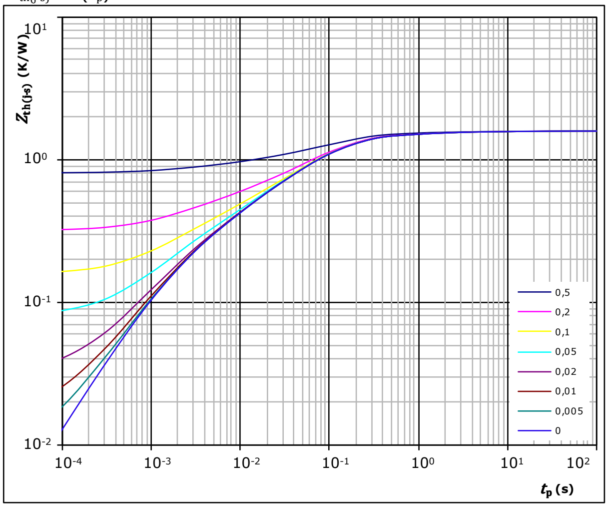
t_p = 250 µs

T_j: 25 °C ············ / 125 °C ———

figure 2. **Rectifier Diode**

Transient thermal impedance as a function of pulse width

$Z_{th(j-s)} = f(t_p)$



$D = t_p / T$

$R_{th(j-s)}$ = 1,59 K/W

Diode thermal model values

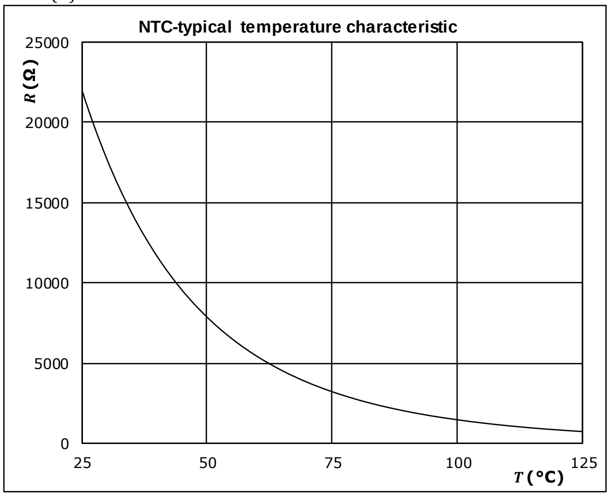
R (K/W)	τ (s)
3,44E-02	9,66E+00
1,12E-01	1,22E+00
5,81E-01	1,45E-01
4,89E-01	5,05E-02
2,38E-01	9,26E-03
1,22E-01	1,79E-03
1,81E-02	7,88E-04

Thermistor Characteristics

figure 1. **Thermistor**

Typical NTC characteristic as a function of temperature

$R = f(T)$

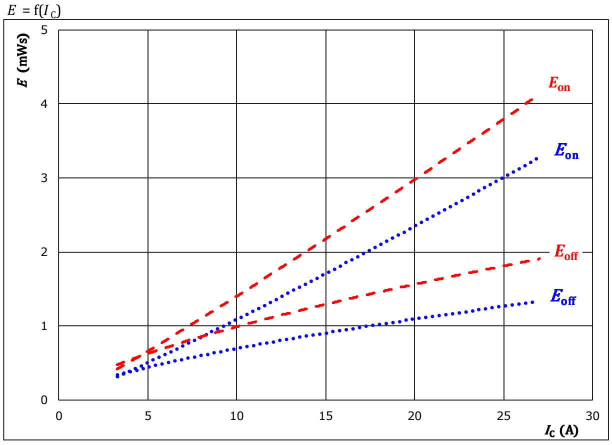


Inverter Switching Characteristics

figure 1. **IGBT**

Typical switching energy losses as a function of collector current

$E = f(I_C)$



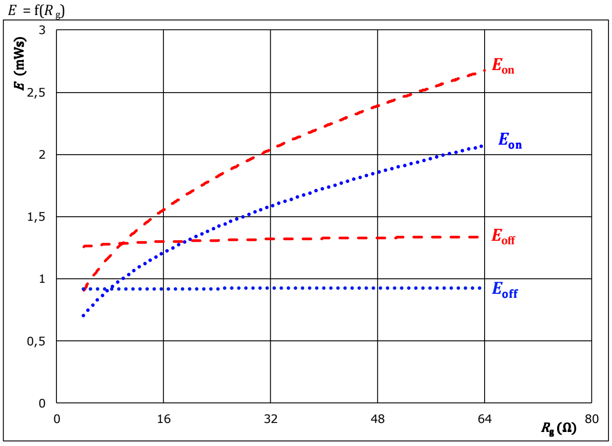
With an inductive load at T_j: 25 °C (dotted), 150 °C (dashed)

V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω
R_{goff} = 32 Ω

figure 2. **IGBT**

Typical switching energy losses as a function of gate resistor

$E = f(R_g)$



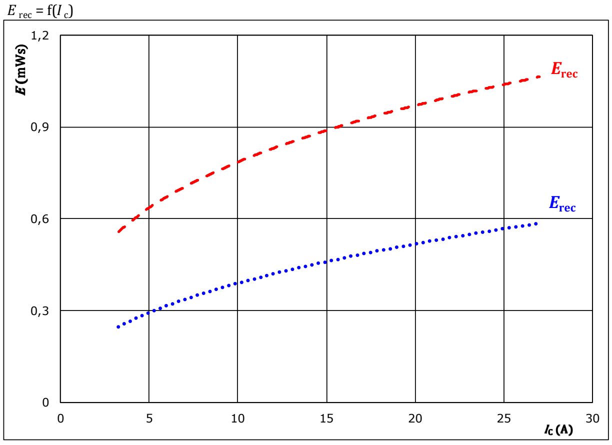
With an inductive load at T_j: 25 °C (dotted), 150 °C (dashed)

V_{CE} = 600 V
V_{GE} = ±15 V
I_C = 15 A

figure 3. **FWD**

Typical reverse recovered energy loss as a function of collector current

$E_{rec} = f(I_C)$



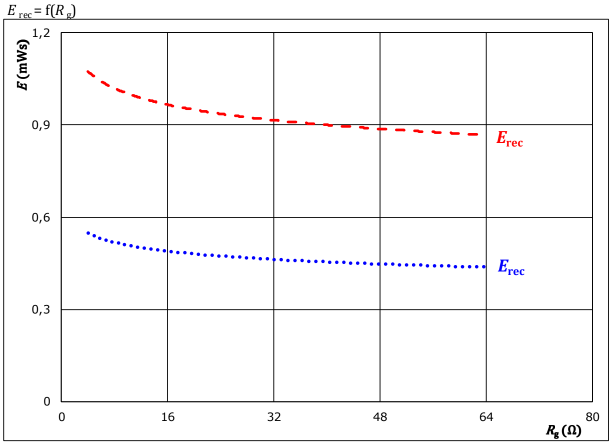
With an inductive load at T_j: 25 °C (dotted), 150 °C (dashed)

V_{CE} = 600 V
V_{GE} = ±15 V
R_{gon} = 32 Ω

figure 4. **FWD**

Typical reverse recovered energy loss as a function of gate resistor

$E_{rec} = f(R_g)$



With an inductive load at T_j: 25 °C (dotted), 150 °C (dashed)

V_{CE} = 600 V
V_{GE} = ±15 V
I_C = 15 A

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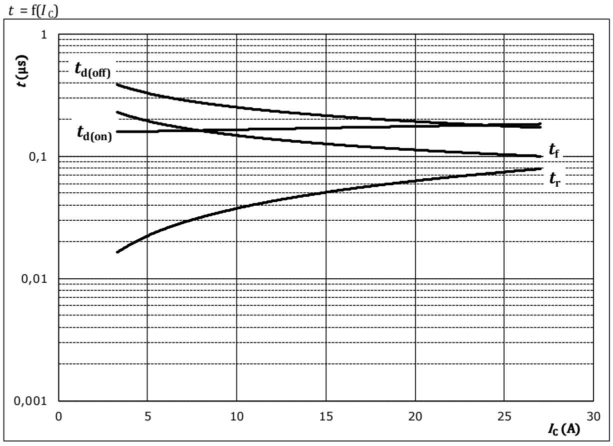
Vincotech

Inverter Switching Characteristics

figure 5. **IGBT**

Typical switching times as a function of collector current

$t = f(I_C)$



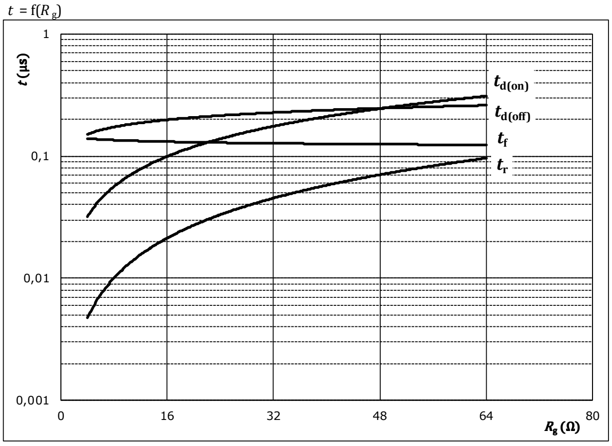
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
R_{gon} =	32	Ω
R_{goff} =	32	Ω

figure 6. **IGBT**

Typical switching times as a function of gate resistor

$t = f(R_g)$



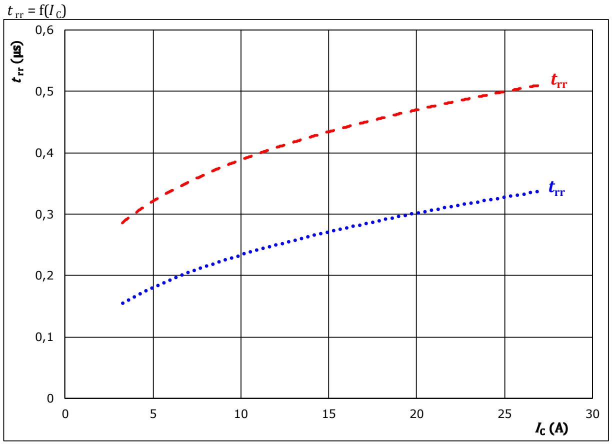
With an inductive load at

T_j =	150	°C
V_{CE} =	600	V
V_{GE} =	±15	V
I_C =	15	A

figure 7. **FWD**

Typical reverse recovery time as a function of collector current

$t_{rr} = f(I_C)$

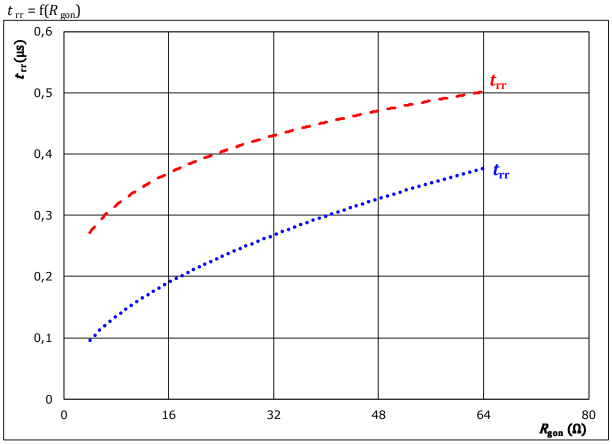


At						
V_{CE}	600	V		25	°C	···········
V_{GE} =	±15	V	T_j:	150	°C	– – – – –
R_{gon} =	32	Ω				

figure 8. **FWD**

Typical reverse recovery time as a function of IGBT turn on gate resistor

$t_{rr} = f(R_{gon})$



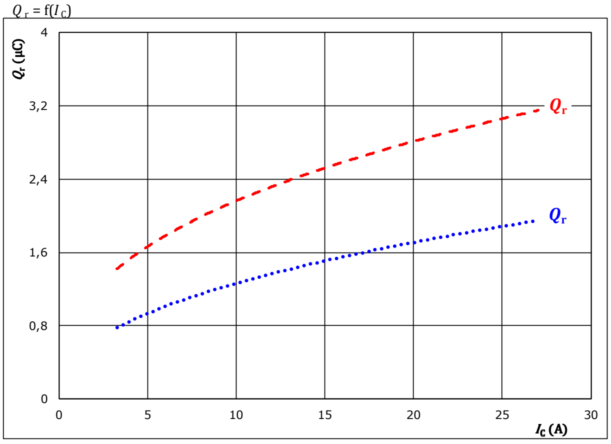
At						
V_{CE}:	600	V		25	°C	···········
V_{GE} =	±15	V	T_j:	150	°C	– – – – –
I_C =	15	A				

Inverter Switching Characteristics

figure 9. **FWD**

Typical recovered charge as a function of collector current

$Q_r = f(I_C)$

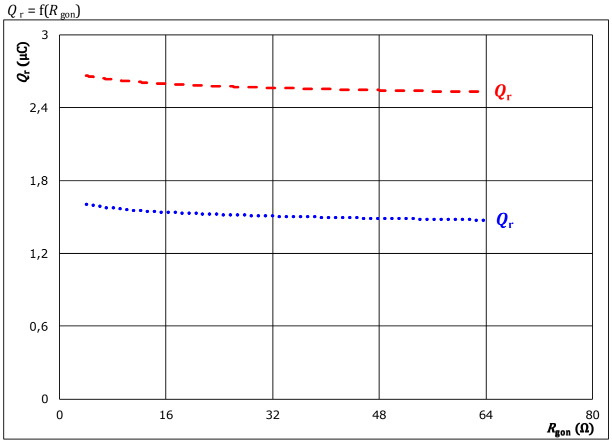


At						
	V_{CE}:	600	V		25 °C	··········
	V_{GE} =	±15	V	T_j:	150 °C	– – – – –
	R_{gon} =	32	Ω			

figure 10. **FWD**

Typical recovered charge as a function of IGBT turn on gate resistor

$Q_r = f(R_{gon})$

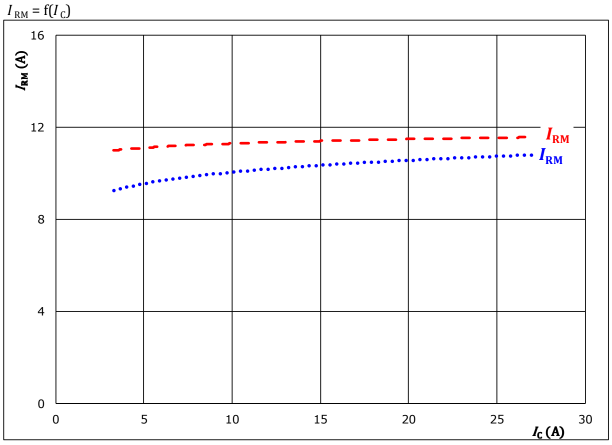


At						
	V_{CE}:	600	V		25 °C	··········
	V_{GE} =	±15	V	T_j:	150 °C	– – – – –
	I_C=	15	A			

figure 11. **FWD**

Typical peak reverse recovery current current as a function of collector current

$I_{RM} = f(I_C)$

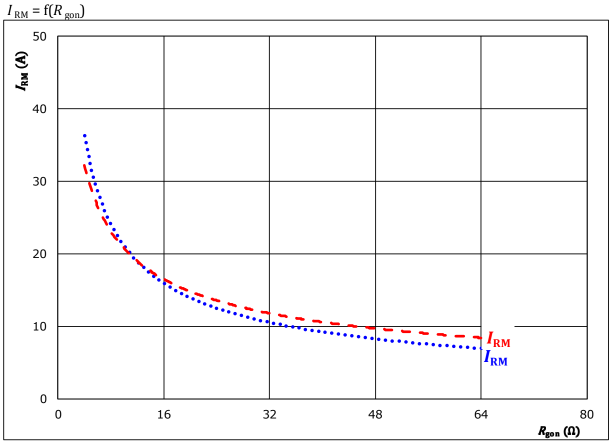


At						
	V_{CE}	600	V		25 °C	··········
	V_{GE} =	±15	V	T_j:	150 °C	– – – – –
	R_{gon} =	32	Ω			

figure 12. **FWD**

Typical peak reverse recovery current as a function of IGBT turn on gate resistor

$I_{RM} = f(R_{gon})$



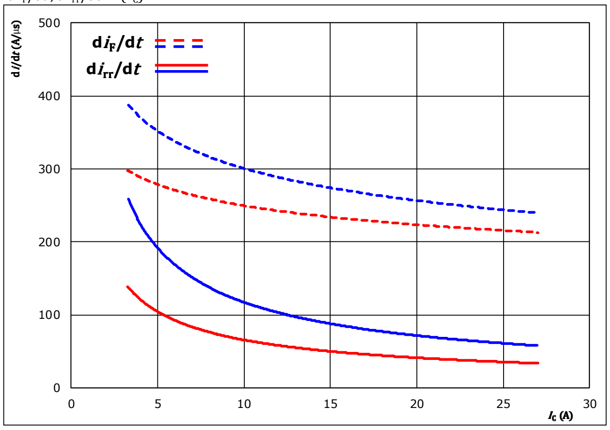
At						
	V_{CE}:	600	V		25 °C	··········
	V_{GE} =	±15	V	T_j:	150 °C	– – – – –
	I_C=	15	A			

Inverter Switching Characteristics

figure 13. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of collector current

$di_F/dt, di_{rr}/dt = f(I_C)$

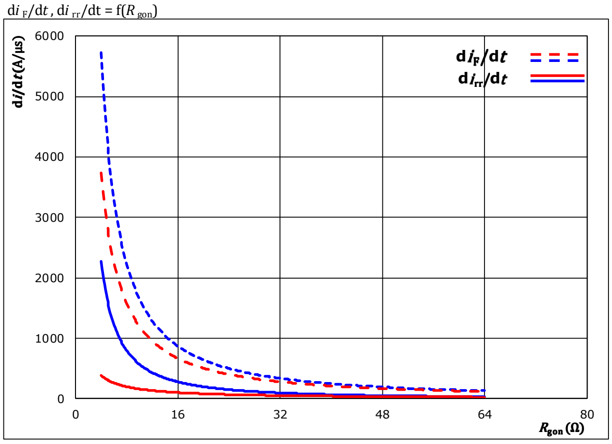


At						
	V_{CE}	600	V		25	°C
	V_{GE} =	±15	V	T_j:	150	°C
	R_{gon} =	32	Ω			

figure 14. **FWD**

Typical rate of fall of forward and reverse recovery current as a function of IGBT turn on gate resistor

$di_F/dt, di_{rr}/dt = f(R_{gon})$

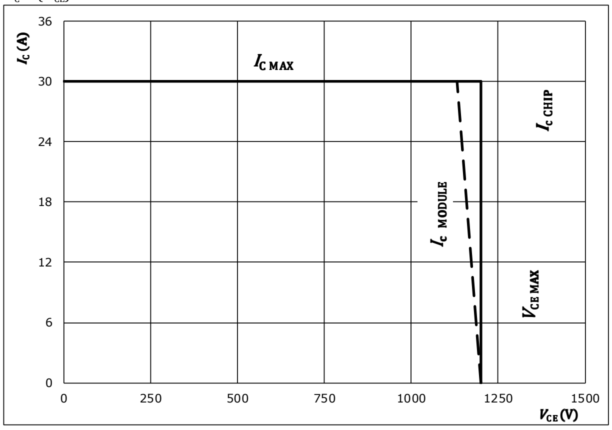


At						
	V_{CE}:	600	V		25	°C
	V_{GE} =	±15	V	T_j:	150	°C
	I_C=	15	A			

figure 15. **IGBT**

Reverse bias safe operating area

$I_C = f(V_{CE})$



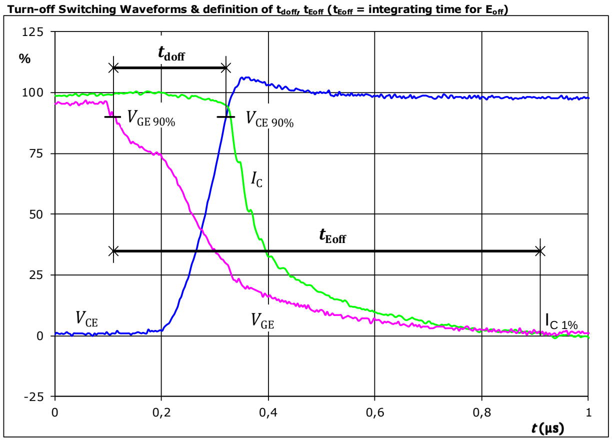
At			
	T_j =	175	°C
	R_{gon} =	32	Ω
	R_{goff} =	32	Ω

Inverter Switching Definitions

General conditions		
T_j	=	**150 °C**
R_{gon}	=	**32 Ω**
R_{goff}	=	**32 Ω**

figure 1. **IGBT**

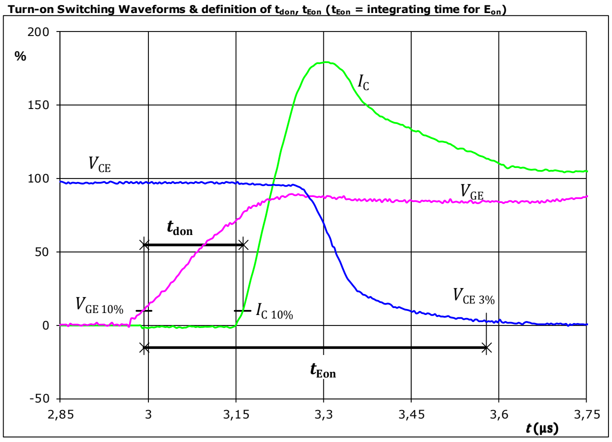
Turn-off Switching Waveforms & definition of t_{doff}, t_{Eoff} (t_{Eoff} = integrating time for E_{off})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{doff} =	0,218	µs
t_{Eoff} =	0,800	µs

figure 2. **IGBT**

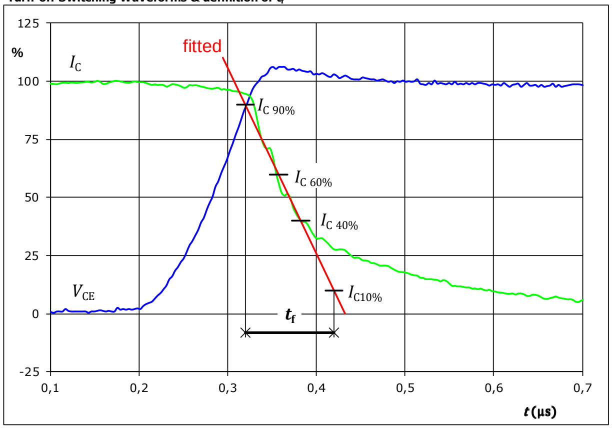
Turn-on Switching Waveforms & definition of t_{don}, t_{Eon} (t_{Eon} = integrating time for E_{on})



$V_{GE}(0\%)$ =	-15	V
$V_{GE}(100\%)$ =	15	V
$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_{don} =	0,174	µs
t_{Eon} =	0,586	µs

figure 3. **IGBT**

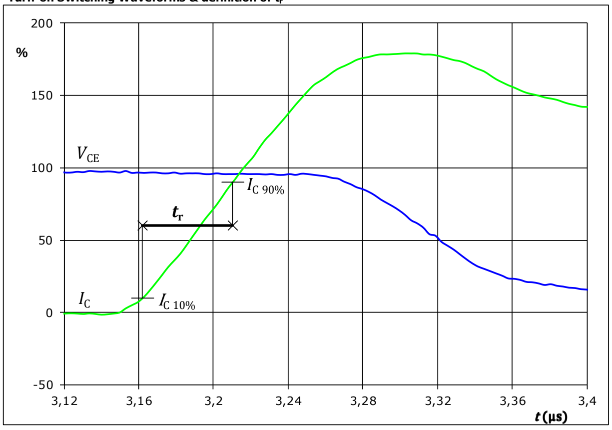
Turn-off Switching Waveforms & definition of t_f



$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_f =	0,127	µs

figure 4. **IGBT**

Turn-on Switching Waveforms & definition of t_r

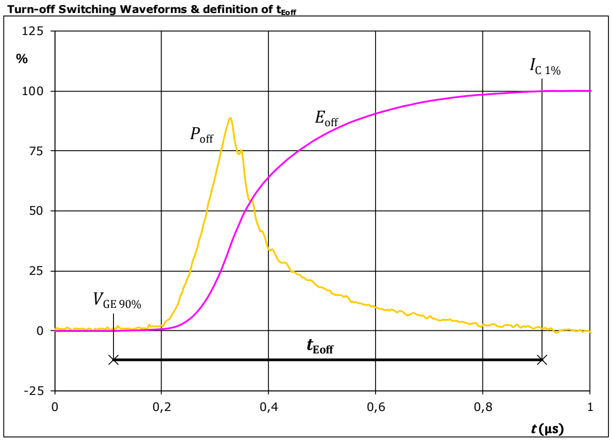


$V_C(100\%)$ =	600	V
$I_C(100\%)$ =	15	A
t_r =	0,048	µs

Inverter Switching Characteristics

figure 5. **IGBT**

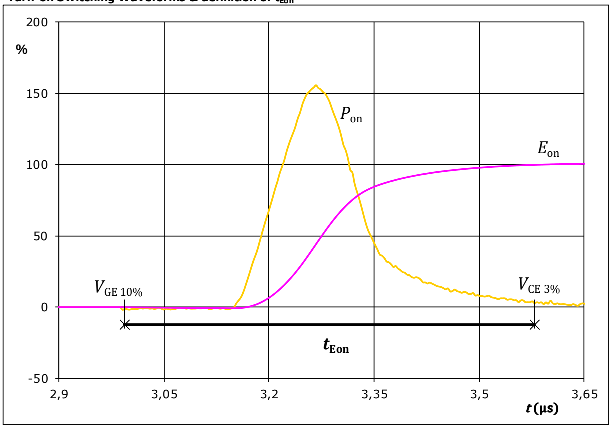
Turn-off Switching Waveforms & definition of t_{Eoff}



P_{off}(100%) =	9,24	kW
E_{off}(100%) =	1,32	mJ
t_{Eoff} =	0,80	µs

figure 6. **IGBT**

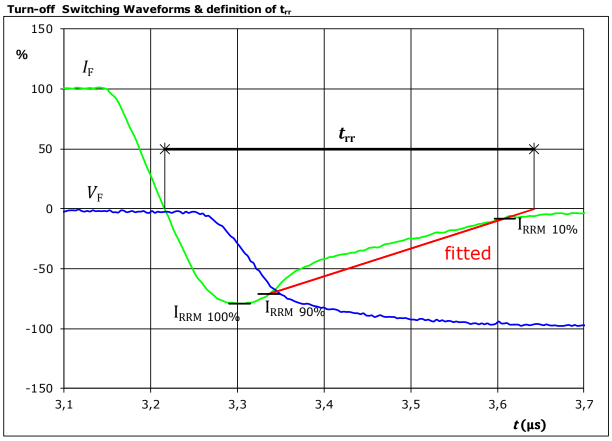
Turn-on Switching Waveforms & definition of t_{Eon}



P_{on}(100%) =	9,24	kW
E_{on}(100%) =	2,01	mJ
t_{Eon} =	0,59	µs

figure 7. **FWD**

Turn-off Switching Waveforms & definition of t_{rr}

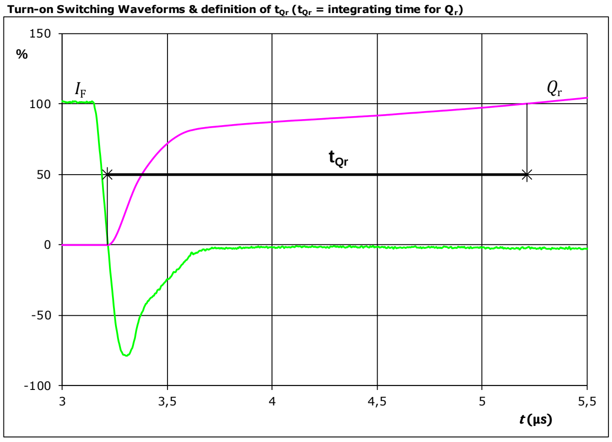


V_F(100%) =	600	V
I_F(100%) =	15	A
I_{RRM}(100%) =	-12	A
t_{rr} =	0,423	µs

Inverter Switching Characteristics

figure 8. FWD

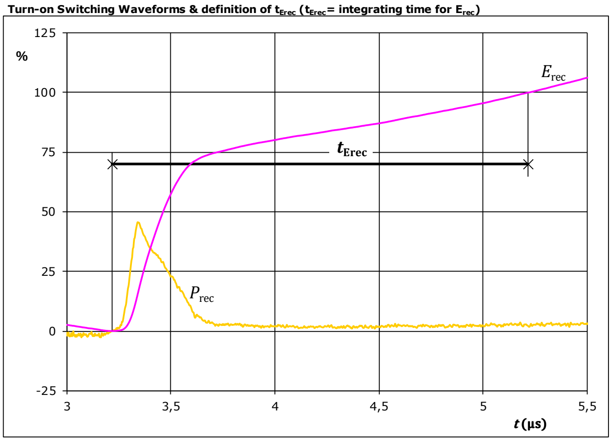
Turn-on Switching Waveforms & definition of t_{Qr} (t_{Qr} = integrating time for Q_r)



I_F(100%) =	15	A
Q_r(100%) =	2,59	µC
t_{Qr} =	2,00	µs

figure 9. FWD

Turn-on Switching Waveforms & definition of t_{Erec} (t_{Erec}= integrating time for E_{rec})



P_{rec}(100%) =	9,24	kW
E_{rec}(100%) =	0,94	mJ
t_{Erec} =	2,00	µs

10-F012PNA015M7-P840C29
datasheet

Vincotech

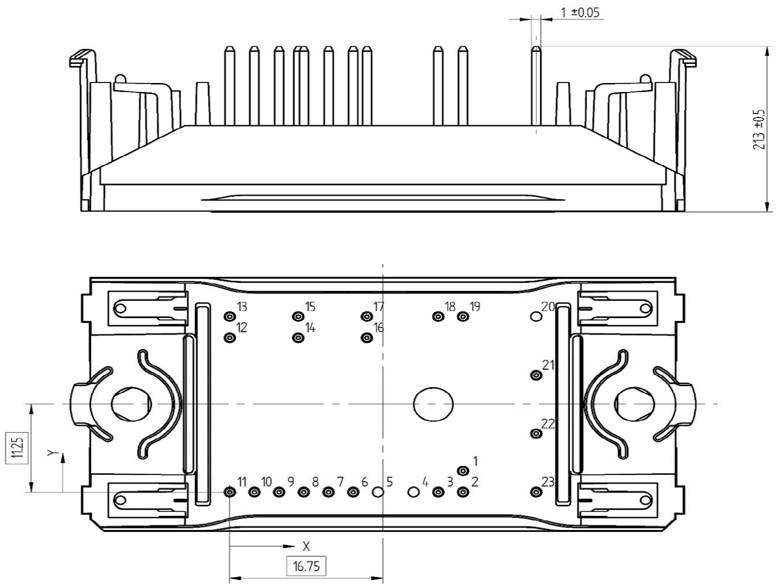
Ordering Code & Marking

Version	Ordering Code
without thermal paste 17 mm housing with solder pins	10-F012PNA015M7-P840C29

	Name		Date code	UL & VIN	Lot	Serial
Text	NN-NNNNNNNNNNNNNN-TTTTTTVV		WWYY	UL VIN	LLLLL	SSSS
	Type&Ver	Lot number	Serial	Date code		
Datamatrix	TTTTTTTVV	LLLLL	SSSS	WWYY		

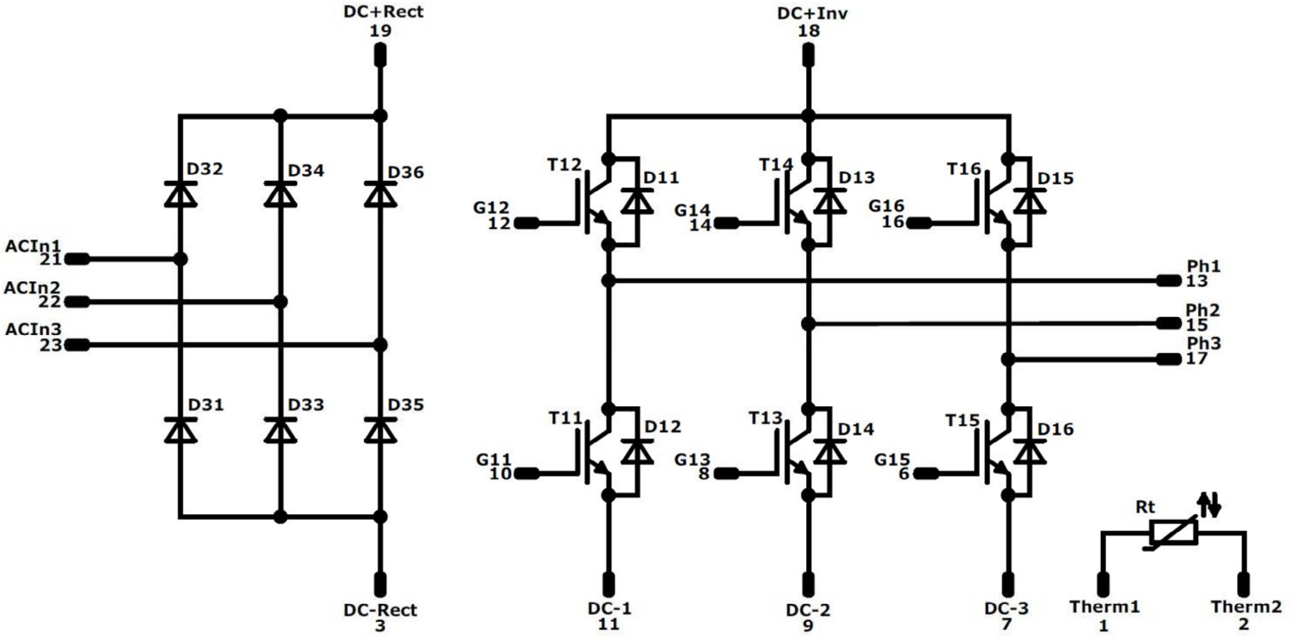
Outline

Pin table			
Pin	X	Y	Function
1	25,5	2,7	Therm1
2	25,5	0	Therm2
3	22,8	0	DC-Rect
4	Not assembled		
5	Not assembled		
6	13,5	0	G15
7	10,8	0	DC-3
8	8,1	0	G13
9	5,4	0	DC-2
10	2,7	0	G11
11	0	0	DC-1
12	0	19,8	G12
13	0	22,5	Ph1
14	7,5	19,8	G14
15	7,5	22,5	Ph2
16	15	19,8	G16
17	15	22,5	Ph3
18	22,8	22,5	DC+Inv
19	25,5	22,5	DC+Rect
20	Not assembled		
21	33,5	15	ACIn1
22	33,5	7,5	ACIn2
23	33,5	0	ACIn3



Tolerance of pinpositions: ±0.5mm at the end of pins
Dimension of coordinate axis is only offset without tolerance

Pinout



Identification

ID	Component	Voltage	Current	Function	Comment
T11, T12, T13, T14, T15, T16	IGBT	1200 V	15 A	Inverter Switch	
D11, D12, D13, D14, D15, D16	FWD	1200 V	15 A	Inverter Diode	
D31, D32, D33, D34, D35, D36	Rectifier	1600 V	25 A	Rectifier Diode	
Rt	Thermistor			Thermistor	

Packaging instruction				
Standard packaging quantity (SPQ) 135	>SPQ	Standard	<SPQ	Sample

Handling instruction
Handling instructions for *flow* 0 packages see vincotech.com website.

Package data
Package data for *flow* 0 packages see vincotech.com website.

UL recognition and file number
This device is certified according to UL 1557 standard, UL file number E192116. For more information see vincotech.com website.

Document No.:	Date:	Modification:	Pages
10-F012PNA015M7-P840C29-D1-14	26 Jul. 2018	Initial release	